



Test Location and Topside Marking Change for Platform Flash and XC18V Flash Memory Devices

XCN08005 (v1.0) February 16, 2009

Product Change Notice – For Your Information

Overview

The purpose of this document is to communicate a change in the test equipment/location for all devices and the topside part marking for many devices in the Platform Flash (XCF) and XC18V families of flash memory configuration devices. There is no change to the fit or function of these devices. The form of these devices is changing with topside marking changes only for those packages with physical space for a test site identifier.

Description

Final test of all Platform Flash (XCF) and XC18V families is expected to change from the Amkor Philippines test facility to the Numonyx test facility in Muar, Malaysia (Table 1). The test program specification will not change.

This change will improve the ability of Xilinx to support this product effectively and to accommodate high-volume demand. There is no change in test program specification associated with this notification. The fit and function of devices tested at Amkor, Philippines and Muar will be the same. There is no change to the device IDCODE. Xilinx iMPACT software and recommended third party programming software will not be affected by this change.

Table 1: Test Facility Location Change Summary

Xilinx Family	Change Description
XCFxx / XQFxx	Final Test Location Changes from Amkor Philippines to Muar, Malaysia
XC18Vxx/XQ18Vxx	Final Test Location Changes from Amkor Philippines to Muar, Malaysia

Topside marking of these devices will be changing with the removal of a test site identifier '7B' from the topside marking for those packages with physical space for this identifier. In addition, from this date forward, this identifier will no longer be a guarantee of testing at the Amkor Philippines test site. Xilinx can provide test site traceability if required. There is no change to the device IDCODE. Xilinx iMPACT software and recommended third party programming software will not be affected by this change.

After the release of this notice, customers may receive devices tested at either the Amkor Philippines or Muar, Malaysia facilities, marked with a '7B' or not, until all inventory from the Amkor Philippines facility and/or marked with the '7B' identifier is depleted.

Figure 1 is a graphical representation of the change in topside mark for the XCF08P device. This graphical representation will be visible on all packages with physical space for the '7B' code.

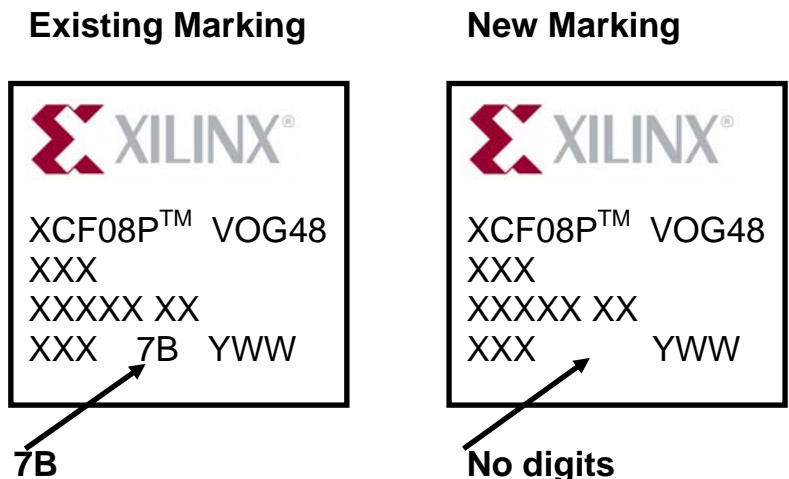


Figure 1: XCF08P Sample Marking Change

Products Affected

This change affects all devices from Platform Flash XCF and XC18V flash memory configuration devices. This includes Q grade devices. Affected part numbers are included in Table 2 below.

Table 2: Affected Products

XC18V Family			
XC18V01PC20C	XC18V02PC44C	XC18V04PC44C	XC18V512PC20C
XC18V01PCG20C	XC18V02PCG44C	XC18V04PCG44C	XC18V512PCG20C
XC18V01SO20C	XC18V02VQ44C	XC18V04VQ44C	XC18V512SO20C
XC18V01SOG20C	XC18V02VQG44C	XC18V04VQG44C	XC18V512SOG20C
XC18V01VQ44C		XQ18V04VQ44N	XC18V512VQ44C
XC18V01VQG44C			XC18V512VQG44C

Platform Flash Family			
XCF01SVO20C	XCF08PFS48C	XCF16PFS48C	XCF32PFS48C
XCF01SVOG20C	XCF08PFSG48C	XCF16PFSG48C	XCF32PFSG48C
XCF02SVO20C	XCF08PVO48C	XCF16PVO48C	XCF32PVO48C
XCF02SVOG20C	XCF08PVOG48C	XCF16PVOG48C	XCF32PVOG48C
XCF04SVO20C			XQF32PVO48M
XCF04SVOG20C			
XCF128XFT64C*			
XCF128XFTG64C*			

*These two devices are affected by the topside marking change only; they are already tested in the Muar, Malaysia facility and have been tested in that facility since their production release.

Traceability

Xilinx can provide final test location traceability shipped devices, if required. From this date forward it will not be possible to determine the final test location by the device top marking.

Qualification Data

Final test correlation data is available and provided with this notification.

[RPT118 - Platform Flash and XC18V Flash Memory Device Test Location Change Qualification Report](#)

Response

No response is required. For additional information or to provide feedback on this draft notification, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
02/16/09	1.0	Initial Release

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